

Title (en)
APPARATUS FOR CLEANING POT-SHAPED HOLLOW BODIES, IN PARTICULAR TRANSPORT CONTAINERS FOR SEMICONDUCTOR WAFERS OR FOR EUV LITHOGRAPHY MASKS

Title (de)
VORRICHTUNG ZUM REINIGEN VON TOPFFÖRMIGEN HOHLKÖRPERN, INSBESONDERE VON TRANSPORTBEHÄLTERN FÜR HALBLEITERWAFER ODER FÜR EUV-LITHOGRAFIE-MASKEN

Title (fr)
APPAREIL DE NETTOYAGE DE CORPS CREUX EN FORME DE POT, EN PARTICULIER DES RÉCIPIENTS DE TRANSPORT POUR TRANCHES SEMI-CONDUCTRICES OU POUR MASQUES DE LITHOGRAPHIE EUV

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Abstract (en)
[origin: WO2022096657A1] The present invention relates to an apparatus (10) for cleaning pot-shaped hollow bodies (12), in particular transport containers (30) for semiconductor wafers or for EUV lithography masks, wherein the apparatus (10) comprises: a support wall (20) onto which the hollow body (12) can be placed by way of its edge surface (38); a locking device (26) by means of which the hollow body (12) can be sealingly and releasably connected to the support wall (20); at least one passage opening (24) which is formed by the support wall (20) and is arranged radially within the locking device (26); a cleaning device (40) by means of which a first cleaning fluid can be dispensed for cleaning the hollow body inner surface (33) when the hollow body (12) is connected to the support wall (20); and a first discharge channel (70) with a first end (72), wherein the first discharge channel (70) with the first end (72) is in fluidic communication only with the passage opening (24) and with which the first cleaning fluid dispensed by the cleaning device (40) can be discharged.

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